ABSTRACT

A novel polyimide copolymer, which is a copolymer comprising two kinds of tetracarboxylic acid dianhydrides consisting of (A) isopropylidene-bis(4-phenyleneoxy-4-phthalic acid) dianhydride and (B) 3,3′ ,4,4′ -biphenyltetracarboxylic acid dianhydride, and one kind of a diamine consisting of (C) 6-amino-2-(p-aminophenyl)benzimidazole, or two or three kinds of diamines consisting of component (C) and (D) at least one kind of diamines consisting of bis(4-amino-phenyl)ether (D_1) and phenylenediamine (D_2), and a metal laminate manufactured by laminating said polyimide copolymer to a metallic foil. The metal laminate comprising the novel polyimide copolymer as a layer on the metallic foil has a low curling susceptibility to cause curling, twisting, warping, etc. against temperature changes due to a low coefficient of linear thermal expansion of the polyimide copolymer, and also has satisfactory adhesiveness and thermal dimensional stability and a low water absorbability, and thus can be used as a suitable for a flexible, finely printed circuit board requiring a high dimensional stability.